

Delton Electronics Inc.

OUT-GOING INSP.REPORT

Customer	大眾
Customer P/N	GTA02-SUB-A2
Part Number	06KT49360B0A
D/C	0734
Quantity	60 PCS

Check by	<i>Rusky_Wang</i>	Approved by	<i>Susan</i>
Prepared by	Ying_Li	Build Date	2007.08.22

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7. Customer Drawing &COC
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QA Check-list

No.	Contents	Item	Check	Requirement	Result	Comments
1	VISUAL	1-1. All Item	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on Visual Requirement	OK	PASS
2	Dimension Measurement	2-1. Outside	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
		2-2. Hole Size	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
		2-3. Trough Width	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
		2-4. Board Thickness	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
		2-5. Au/Ni Thickness	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
		2-6. Dielectric Thickness	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
3	Impedance Measurement	3-1. Indentity	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	To depend on customer information	OK	PASS
4	Reliability Test	3-2. Differentialaction	<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	N/A	N/A	N/A
		4-1. Thermal Stress	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	No excessive voids, crack	OK	PASS
		4-2. Solderability	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	>95%	OK	PASS
		4-3. Ionic Contamination Test	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No	$\leq 6.45\mu\text{g NaCl/sq.in}$	1.5 ug NaCl/sq.in	PASS

A. VISUAL (外觀檢驗)

ITEM	REQUIREMENT	RESULT	AC	RE	ITEM	REQUIREMENT	RESULT	AC	RE
MATERIAL	FR-4	FR-4	✓		PEELING TEST	NO PEEL OFF	PASS	✓	
BOARD THK	0.0305±0.00304"	0.03055±0.03270"	✓		DATE CODE	YYWW	0734	✓	
LINE WIDTH	0.0040"	0.00412"	✓		UL MARK	DT1 BV-1	DT1 BV-1	✓	
SPACING	0.0040"	0.00420"	✓		O/S TEST	100% TEST	PASS	✓	
ANNULAR RING	0.002"	0.002"	✓		WARP&TWIST	≤0.70%	0.11±0.23%	✓	
SOLDER MASK	Blue	Blue	✓						
LEGEND	White	White	✓						

B. HOLE SIZE: (UNIT: INCH) 表三NON-PTH (孔徑)

NO	REQUIREMENT	TOLERANCE(+)	RESULT	AC	RE	NO	REQUIREMENT	TOLERANCE(+)	RESULT	AC	RE
1	0.0120	0.003	0.0120 ~ 0.0120	✓		26					
*2	0.0190/0.0170/0.0157	0.002	0.0200 ± 0.0710	✓		27					
*3	0.1575	0.002	0.1560 ~ 0.1575	✓		28					
4	END					29					
5						30					
6						31					
7						32					
8						33					
9						34					
10						35					
11						36					
12						37					
13						38					
14						39					
15						40					
16						41					
17						42					
18						43					
19						44					
20						45					
21						46					
22						47					
23						48					
24						49					
25						50					

DISPOSITION:

■ ACC

□ REJ

□ UAI

C. OUTSIDE DIMENSIONS(UNIT - INCH)											
NO	REQUIREMENT	TOLERANCE(+)	RESULT	AC	RE	NO	REQUIREMENT	TOLERANCE(+)	RESULT	AC	RE
1	4.00mm	0.20mm	4.00mm ± 4.01mm	✓		26					
2	0.197	0.008	0.197 ± 0.197	✓		27					
3	0.197	0.008	0.196 ± 0.197	✓		28					
4	0.709	0.008	0.709 ± 0.710	✓		29					
5	1.102	0.008	1.100 ± 1.102	✓		30					
6	0.709	0.008	0.707 ± 0.709	✓		31					
7	1.498	0.008	1.495 ± 1.496	✓		32					
8	2.283	0.008	2.283 ± 2.285	✓		33					
9	3.070	0.008	3.069 ± 3.070	✓		34					
10	0.394	0.008	0.393 ± 0.394	✓		35					
11	1.496	0.008	1.495 ± 1.496	✓		36					
12	2.598	0.008	2.598 ± 2.599	✓		37					
13	2.992	0.008	2.990 ± 2.992	✓		38					
14	EN31					39					
15						40					
16						41					
17						42					
18						43					
19						44					
20						45					
21						46					
22						47					
23						48					
24						49					
25						50					
E. REMARK											

DISPOSITION:

☒ ACC☐ REJ☐ UAI

Plated Microsection Inspection Report

廠內料號	Work Time	No.	銅厚(Tenting)						Total Copper (總銅平均值)		Tin(錫)		Registration (對準度)	Etchback (回蝕)	Roughness (粗糙度)	Lamination		
			Side(面)		Hole(孔)													
			1	II	1	2	3	4	5	6	Side	Hole				Side	Hole	(疊合結構)
06KT49360B0A		1	1.51	1.16	1.08	1.13		1.50	1.12			1.19	0.36	0.35	COPPER	1.30	1.472	
		2	1.48	1.00	1.18	1.17								PP1078 61%	2.49	2.468		
		1	1.53	1.20	1.11	1.15								COPPER	0.5 oz	0.672		
	08/22	2	1.49	1.08	1.14	1.16		1.51	1.14			1.13	0.36	0.32	PP1080 61%	2.50	2.514	
														COPPER	1 oz	1.214		
														FR-4	12.00	11.859		
GTA02-SUB-A2		2	1.49	1.08	1.14	1.16								COPPER	1 oz	1.198		
														PP1080 61%	2.50	2.486		
														COPPER	0.5 oz	0.701		
		1	1.46	1.09	0.99	1.10								PP1078 61%	2.49	2.479		
														COPPER	1.30	1.511		
		2	1.50	1.15	1.13	1.18		1.48	1.11			1.17	0.37	0.37				

Unit:(mil)

DISPOSITION:

☒ ACC

☐ REJ

☐ UAI

Delton Technology Incorporated SOLDERABILITY TEST REPORT

TEST CONDITION AND RESULT							
CONDITION		REQUIREMENT		ACTUAL RESULTS			
SOLDER TEMPERATURE		245±5°C		250°C			
DIP TIME		3~5 s		5 s			
RESULT							
DATE	CUSTOMER P/N	DELTON P/N	D/C	TOTAL HOLES	DEWETTING HOLES	RESUL T(ppm)	AC RE
Aug.22,2007	GTA02-SUB-A2	06KT49360B0A	0734	2088	0	0	v
REMARK:1.S/S 焊錫面 100%Wetting. 2.C/S 零件面 100%Wetting.							
Check by		Rusky_wang		INSPECTOR		Ying_Li	

DISPOSITION: ☒ ACC ☐ REJ ☐ UAI

Delton Technology (GZ) Incorporated
THERMAL STRESS TEST REPORT

CUSTOMER P/N	GTA02-SUB-A2	DATE CODE	0734
DELTON P/N	06KT49360B0A	DATE OF TEST	Aug 22, 2007
TEST CONDITION AND RESULTS:			
CONDITION	REQUIREMENT	ACTUAL RESULTS	
SOLDER TEMPERATURE	288±5 °C	293 °C	
DIP TIME	10+1/-0 s	11 s	
RESULTS:			
QUANTITY BOARDS TESTED		AC	RE
PASS	FAIL	REMARK	
4	0	V	NO CRACK
REMARK: 1. Hot Wall : No Crack , No Separation 2. Laminate : No Delamination, No Blistering 3. Solder Mask: No Peel Off, No Crack.			
Check by	<i>Rui Wang</i>	INSPECTOR	Ying_Li

DISPOSITION: ☒ ACC ☐ REJ ☐ UAI

Open&Short Circuit Test

Tester Model:	8000HV
Test Voltage:	250V
Test Current:	20mA
Isolation Resistance:	10M Ω
Continuity Resistance:	20 Ω
Test Result:	PASS

DISPOSITION:

☒ ACC

☐ REJ

☐ UAI

Delton Electronics Inc.

Customer Drawing &COC

Date:	2007.08.22
D/C:	0734
CUSTOMER:	大眾
P.O.#:	
PART#:	GTA02-SUB-A2
QUANTITY:	60 PCS

We hereby certify the materials listed above to be in compliance with the terms and conditions of your purchase order ,including all applicable drawings and specifications. meet or exceed U.L. flame classification 94V--0.
Inspection records and test date necessary to substantiate this certification are on file.

Ch-shieh

Certificate of Compliance

Certificate Number 20040127-E237771

Report Reference E237771, 2003 October 30

Issue Date 2004 January 27

Page 1 of 1



**Underwriters
Laboratories Inc.**

Issued to: **Delton Technology (Guangzhou) Inc.**
22 Baoyingnan Rd., The Computer Industrial City of GZ FTZ, Guangzhou,
Guangdong 510730, China

*This is to certify that
representative samples of*

Wiring, Printed

Multilayer Printed Wiring Boards Employing Rigid Core and High Density
Interconnect (HDI) Material, Type BV-1.

Multilayer Printed Wiring Board, Types ML-1 and ML-2


*Have been investigated by Underwriters Laboratories Inc.® in
accordance with the Standard(s) indicated on this Certificate.*

Standard(s) for Safety: UL 796, Printed-Wiring Boards

Additional Information:

The wiring printed category covers printed wiring boards for use as components in devices or appliances. The boards may use organic or inorganic base materials in a single or multilayer, rigid or flexible form. Circuitry construction may include etched, die stamped, precut, flush press, additive, and plated conductor techniques. Printed-component parts may be used. The suitability of the pattern parameters, temperature and maximum solder limits shall be determined in accordance with the applicable end-product construction and requirements.

Only those products bearing the UL Recognized Component Marking should be considered as being covered by UL's Recognition and Follow-Up Service.

The UL Recognized Component Marking generally consists of the manufacturer's identification and catalog number, model number or other product designation as specified under "Marking" for the particular Recognition as published in the appropriate UL Directory. As a supplementary means of identifying products that have been produced under UL's Component Recognition Program, UL's Recognized Component Mark,  may be used in conjunction with the required Recognized Markings. The Recognized Component Mark is required when specified in the UL Directory preceding the recognitions or under "Markings" for the individual recognitions.

Look for the UL Recognized Component Marking on the product

Issued By:

CHRIS MAK / Project Engineer

UL International Ltd.

Pursuant to the Corporate Services Agreement between UL International Ltd. and Underwriters Laboratories Inc. (UL), UL hereby accredits and issues this Certificate of Compliance. For inquiries in Hong Kong, you may call 852-22769898.

Reviewed By:

CARSON WANG / Manager

UL International Ltd.



Page 1 of 2

Test Report

No.: GZ0608129416/CHEM

Date: AUG 28, 2006

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Results :

(1)

Item	Unit	MDL	Green/ blue "PCB" (mixed)
Lead Content (Pb)	mg/kg	2	5
Cadmium Content (Cd)	mg/kg	2	N.D.
Mercury Content (Hg)	mg/kg	2	N.D.
Hexavalent Chromium Content [Cr(VI)]	mg/kg	2	N.D.

Note : - N.D. = Not Detected (< MDL)
 - MDL = Method Detection Limit
 - mg/kg = ppm

(2)

Item	Unit	MDL	Green/ blue "PCB" (mixed)
Flame Retardants			
Polybrominated Biphenyls (PBBs)			
Monobromobiphenyl	mg/kg	5	N.D.
Dibromobiphenyl	mg/kg	5	N.D.
Tribromobiphenyl	mg/kg	5	N.D.
Tetrabromobiphenyl	mg/kg	5	N.D.
Pentabromobiphenyl	mg/kg	5	N.D.
Hexabromobiphenyl	mg/kg	5	N.D.
Heptabromobiphenyl	mg/kg	5	N.D.
Octabromobiphenyl	mg/kg	5	N.D.
Nonabromodiphenyl	mg/kg	5	N.D.
Decabromodiphenyl	mg/kg	5	N.D.
Polybrominated Diphenylethers (PBDEs)			
Monobromodiphenyl ether	mg/kg	5	N.D.
Dibromodiphenyl ether	mg/kg	5	N.D.
Tribromodiphenyl ether	mg/kg	5	N.D.
Tetrabromodiphenyl ether	mg/kg	5	N.D.
Pentabromodiphenyl ether	mg/kg	5	N.D.
Hexabromodiphenyl ether	mg/kg	5	N.D.
Heptabromodiphenyl ether	mg/kg	5	N.D.
Octabromodiphenyl ether	mg/kg	5	N.D.
Nonabromodiphenyl ether	mg/kg	5	N.D.
Decabromodiphenyl ether	mg/kg	5	N.D.

Note : - N.D. = Not Detected (< MDL)
 - MDL = Method Detection Limit
 - mg/kg = ppm
 - Photo appendix is included

Remark : As requested by client, the test was conducted as whole / part sample.

*** End of Report ***

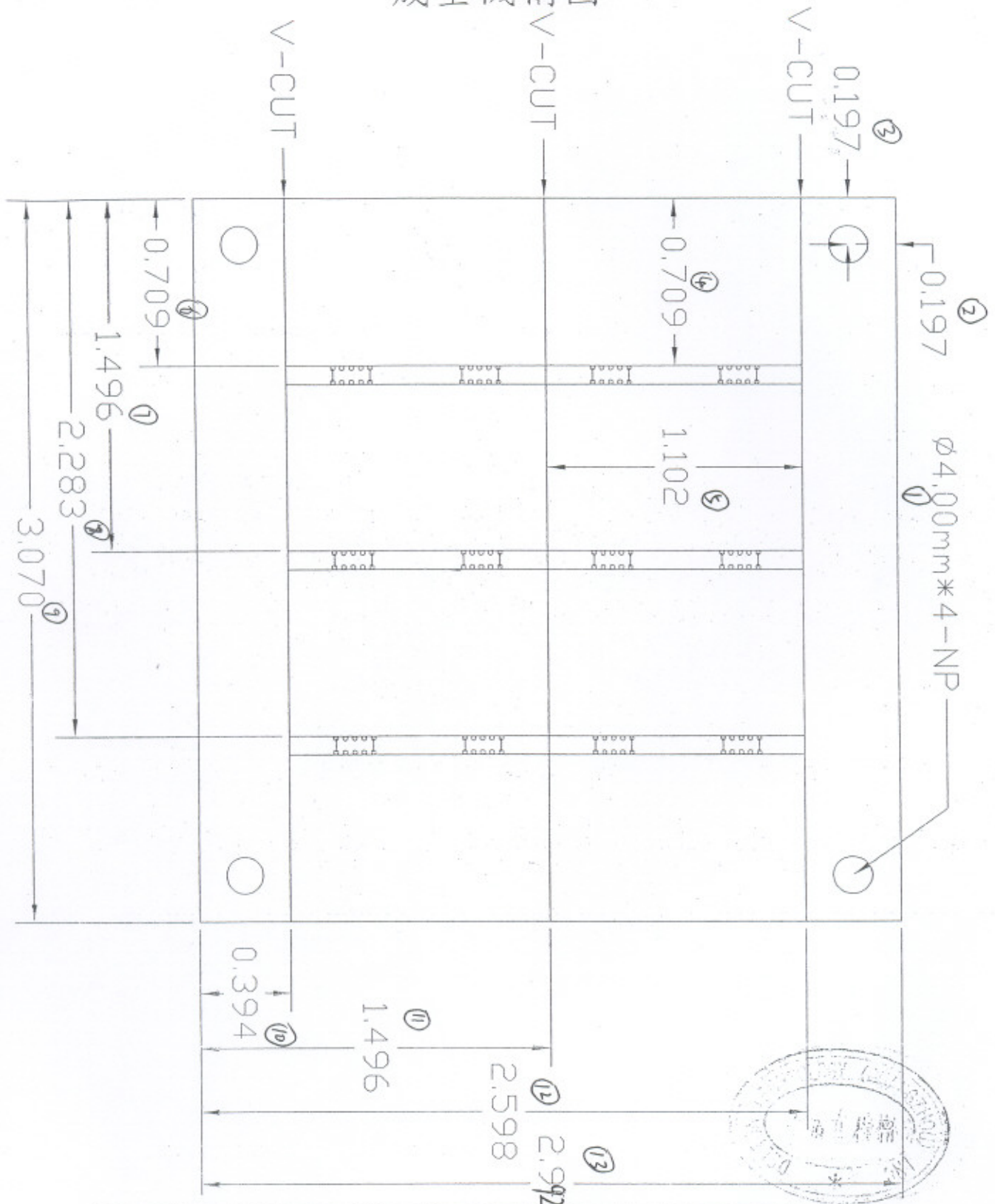
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 SGS (Shanghai) Inspection & Certification Co., Ltd. | 中国·广州·经济技术开发区科学城科苑路198号 邮编 510662 | Tel: +86-20-85155555 | Fax: +86-20-85155556 | Email: sgs@sgs.com.cn

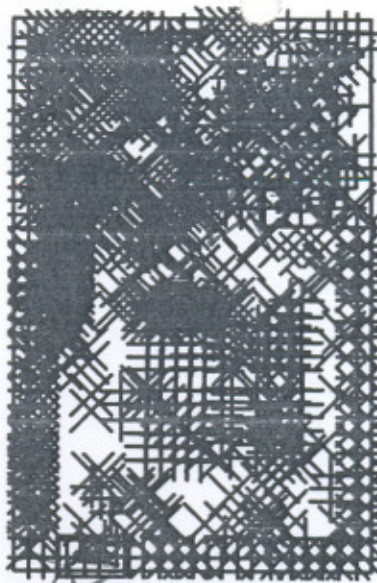
GZCM 949275

成型機構圖



料號:	06KT49360 B0A	單位:	mm	日期:	08/10
尺寸:	2.992" x 3.070"	公差:	±0.008"	製作:	張輝
成型工具:	PIN: Ø3.90mm	圖形VIEW:	CAMP	審核:	許國強 08/10
備註:	V-CUT: 直刀 / 橫刀 3 角度 30±5° 線徑 0.3±0.1mm				

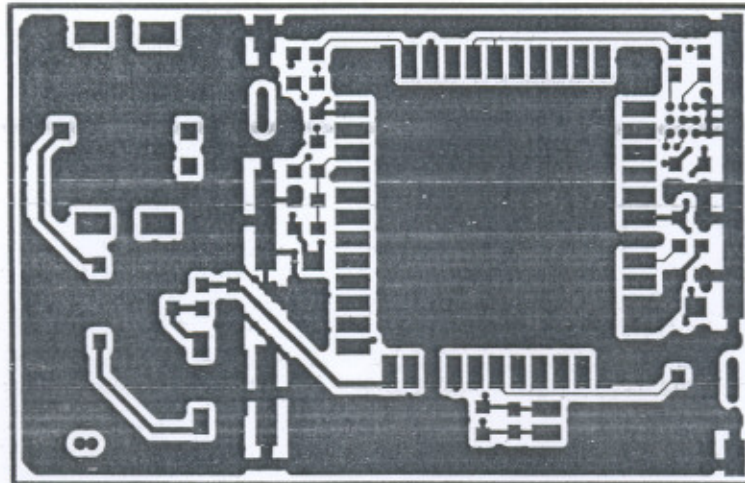
06KT49360 A0A 2007.08.10



SIZE	QTY	SYM	PLATED	TOL.*
12	261	+	YES	+/-0.0
4	490	X	YES	+/-0.0
19.69 x 70.87	2	□	NO	+/-0.0

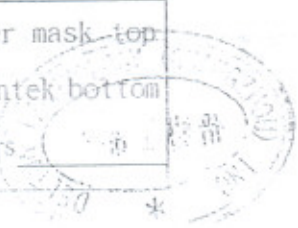
-IC	GTA02		6 LAYER
	WLAN		
LAYER: ° DRILL DRAWING			
DATE: 2007-08-08 14:00			
Clearance error			0
Connectivity error			0

06KT49360 A0A 2007.08.10

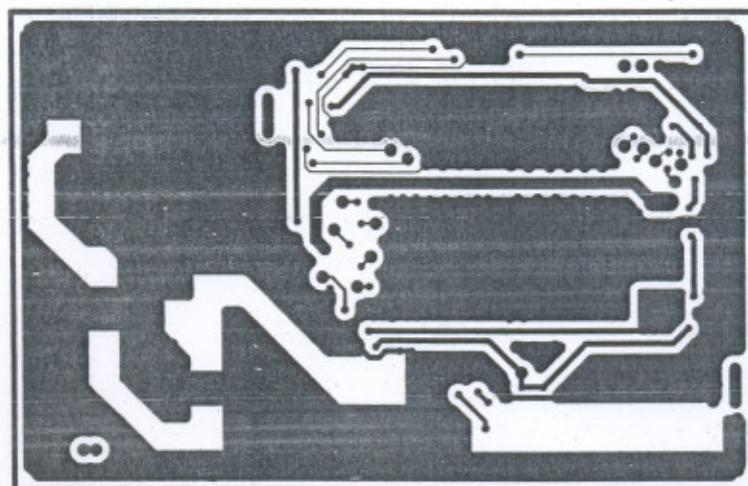


FIC	GTA02	6 LAYER
	WLAN	
LAYER: ○ COMPONENT SIDE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☒ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☐ layer _____ ☐ others _____



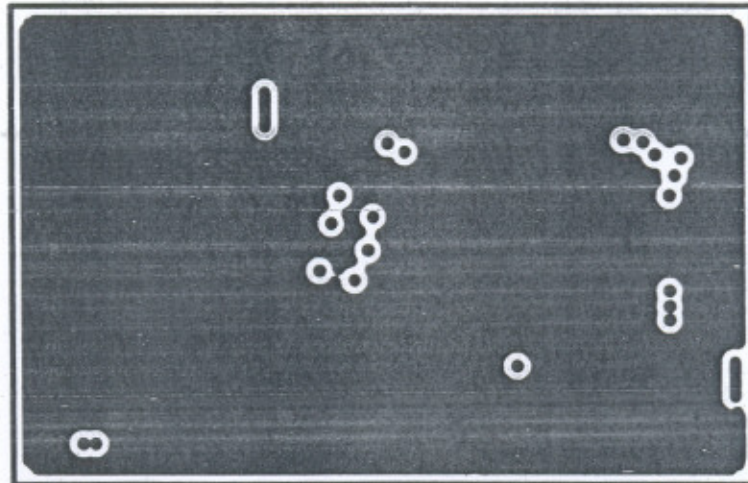
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER: o GND PLANE (INNER) 2		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☒ layer 2 ☐ others 30 *

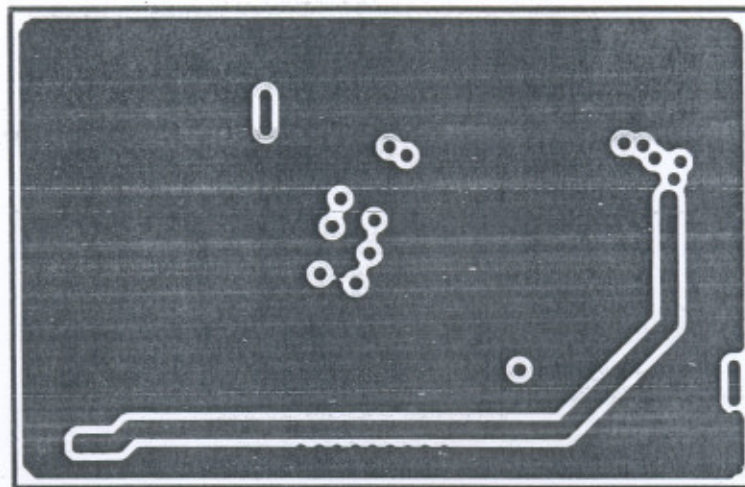
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER: ◦ ARTWORK (INNER) 3		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐top side ☐bottom side ☐silkscreen top ☐silkscreen bottom ☐solder mask top
☐solder mask bottom ☐pastemask top ☐pastemask bottom ☐Entek top ☒Entek bottom
☐Immerse gold top ☐Immerse gold bottom ☐drill map ☒layer 2 ☐others

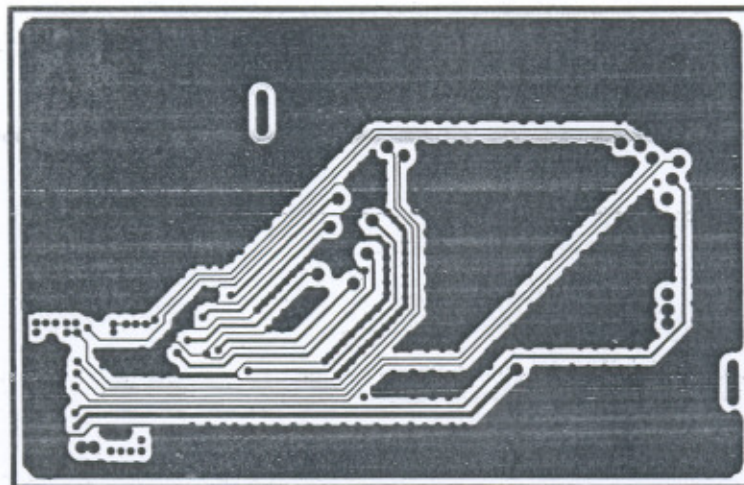
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FIC	GTA02	6 LAYER
	WLAN	
LAYER: ◦ VCC PLANE(INNER) 4		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top ☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom ☐ Immerse gold top ☐ Immerse gold bottom ☒ Drill map ☒ Layer -4 ☐ Others

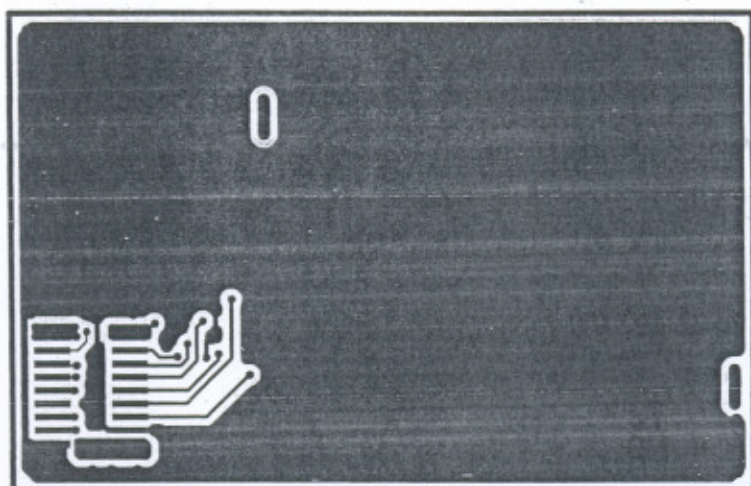
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FIC	GTA02	6 LAYER
	WLAN	
LAYER: o ARTWORK (INNER) 5		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☒ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☒ layer 5 ☐ others *

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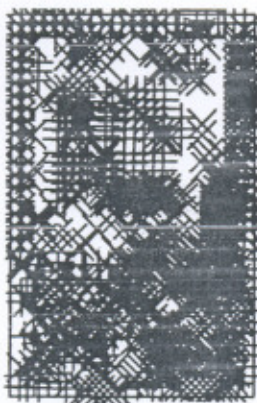


FIC	GTA02	6 LAYER
	WLAN	
LAYER: 0 20LDER 2IDE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☒ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☒ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☒ Layer 6 ☐ others

SIZE	QTY	SYM	PLATED	TOL
12	261	+	YES	+/-0.0
4	490	X	YES	+/-0.0
19.69 x 70.87	2	□	NO	+/-0.0

06KT49360 A0A 2007.08.10



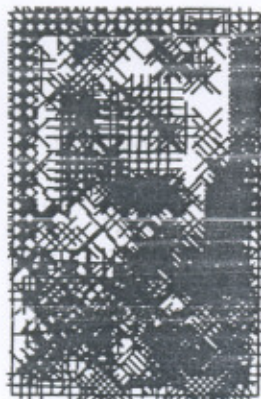
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	WLAN	
LAYER: 0 COMPONENTS/ASSEMBLY		
DATE: 2007-08-08 14:00		
Clearance error	0	
Connectivity error	0	

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☒ drill map ☐ layer ☐ other *



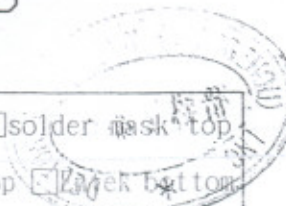
SIZE	QTY	SYM	PLATED	TOL
12	261	+	YES	+/-0.0
4	490	X	YES	+/-0.0
19.69 x 70.87	2	□	NO	+/-0.0

06KT49360 A0A 2007.08.10

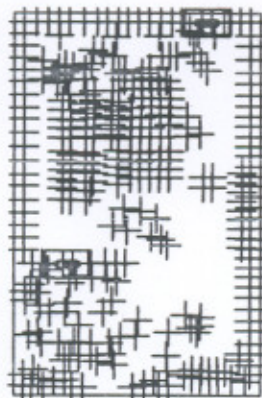


FIC	GTA02	6 LAYER
	WLAN	
LAYER: ° DRILL DRAWING		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold top ☒ drill map ☐ layer ☐ others



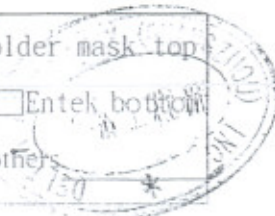
06KT49360 A0A 2007.08.10



SIZE	QTY	SYM	PLATED	TOL
12	314	+	YES	+/-0.0
19.69 x 70.87	2	□	NO	+/-0.0

FIC	GTA02	6 LAYER
	WLAN	
LAYER: VCC DRANE (DRANE)G4		
DATE: 2007-08-08 14:00		
Clearance error	0	
Connectivity error	0	

層別: ☐top side ☐bottom side ☐silkscreen top ☐silkscreen bottom ☐solder mask top
☐solder mask bottom ☐pastemask top ☐pastemask bottom ☐Entek top ☐Entek bottom
☐Immerse gold top ☐Immerse gold bottom ☒drill map ☐layer ☐others

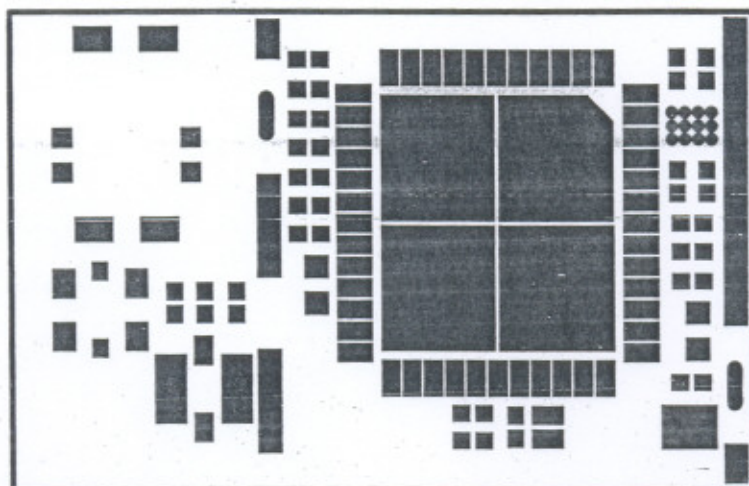


SIZE	QTY	SYM	PLATED	TOL
12	261	+	YES	+/-0.0
4	642	X	YES	+/-0.0
19.69 x 70.87	2	□	NO	+/-0.0

FIC	GTA02	6 LAYER	
	WLAN		
LAYER: ○ B01C1B8BAC0G			
DATE: 2007-08-08 14:00			
Clearence error			0
Connectivity error			0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☐ layer _____ ☐ buffers 備註

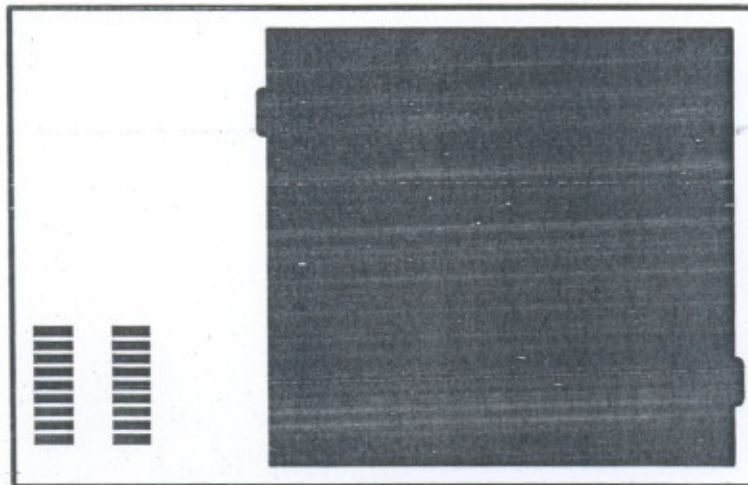
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER: o COMPONENT MASK		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☒ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ Drill map ☐ layer _____ ☐ others _____

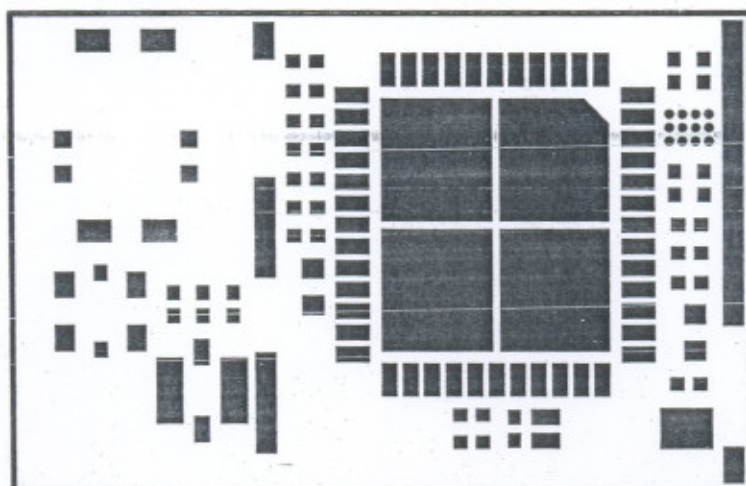
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER: o X2AM 93D102		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☒ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold top ☐ drill map ☐ layer _____ ☐ others

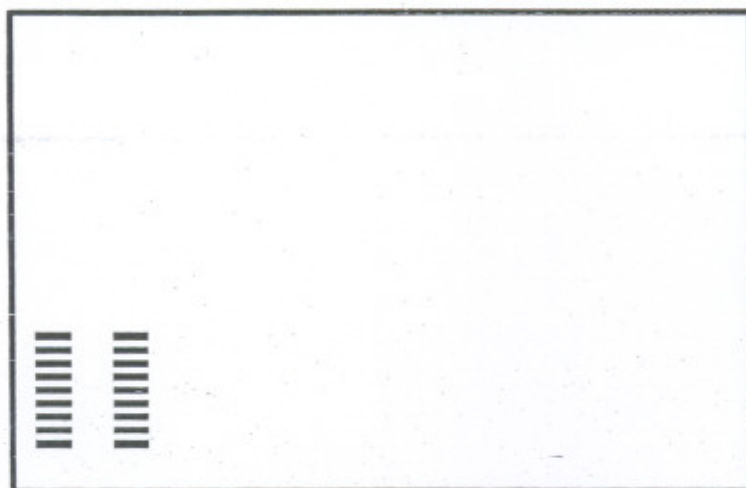
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER:◦ SMD PASTE TOP SIDE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☐ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☒ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☐ layer _____ ☐ others _____

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FIC	GTA02	6 LAYER
	WLAN	
LAYER: 2ND PASTE BOTTOM SIDE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐top side ☐bottom side ☐silkscreen top ☐silkscreen bottom ☐solder mask top
☐solder mask bottom ☐pastemask top ☒pastemask bottom ☐Entek top ☐Entek bottom
☐Immerse gold top ☐Immerse gold bottom ☐drill map ☐layer



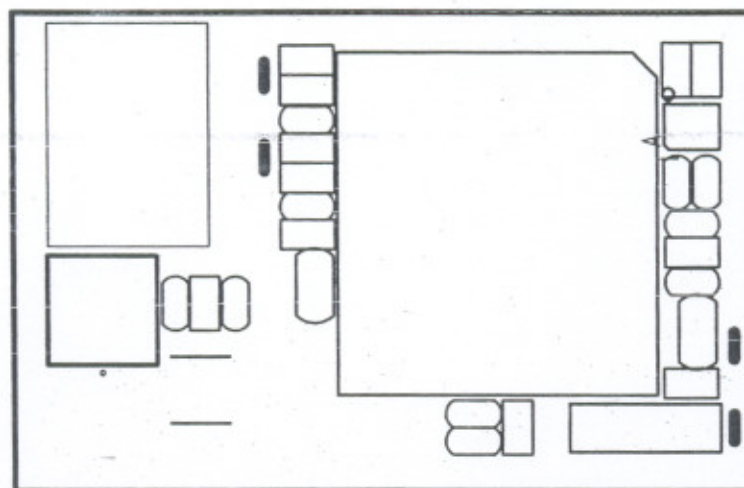
06KT49360 A0A 2007.08.10



FIC	GTA02	6 LAYER
	WLAN	
LAYER: 0 SILKSCREEN BOTTOM SIZE 0 REVERSE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐top side ☐bottom side ☐silkscreen top ☒silkscreen bottom ☐solder mask top
☐solder mask bottom ☐pastemask top ☐pastemask bottom ☐Entek top ☐Entek bottom
☐Immerse gold top ☐Immerse gold bottom ☐drill map ☐layer _____ ☐others/

06KT49360 A0A 2007.08.10



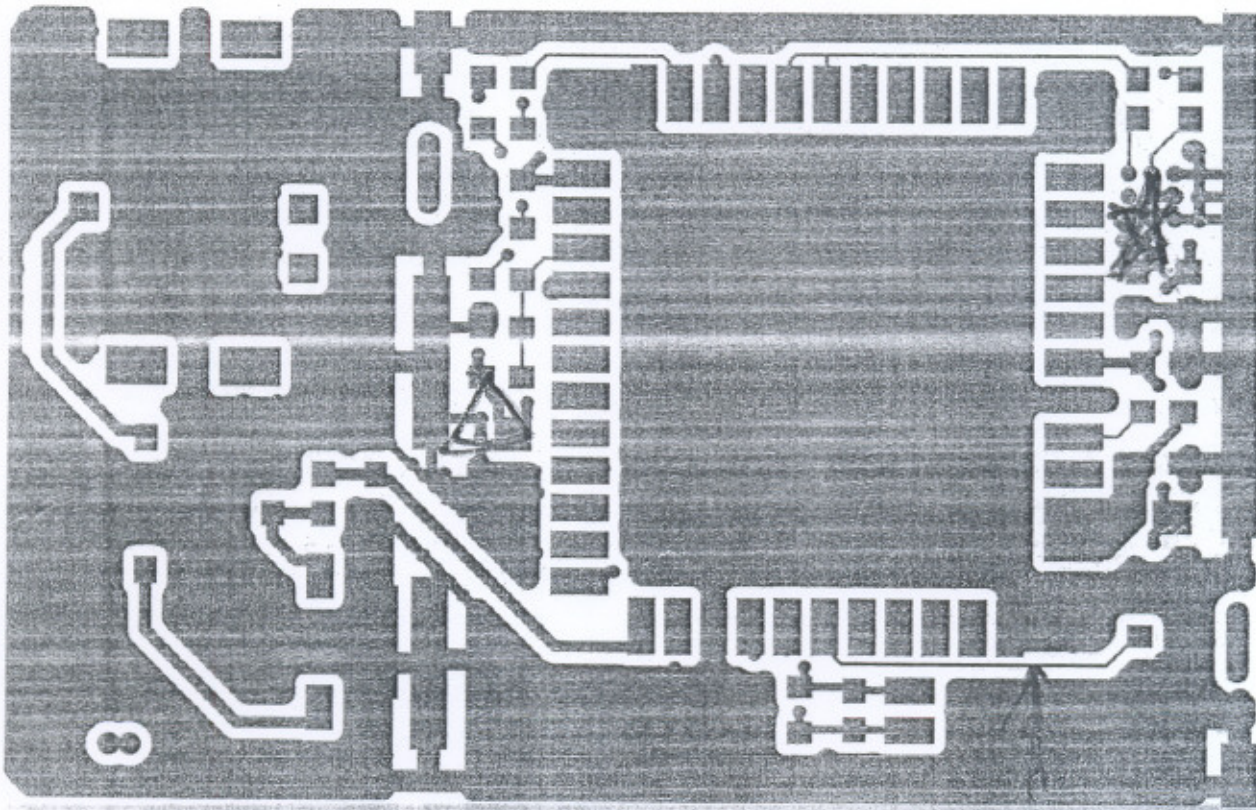
FIC	GTA02	6 LAYER
	WLAN	
LAYER: ◦ SILKSCREEN TOP SIZE		
DATE: 2007-08-08 14:00		
Clearance error		0
Connectivity error		0

層別: ☐ top side ☐ bottom side ☒ silkscreen top ☐ silkscreen bottom ☐ solder mask top
☐ solder mask bottom ☐ pastemask top ☐ pastemask bottom ☐ Entek top ☐ Entek bottom
☐ Immerse gold top ☐ Immerse gold bottom ☐ drill map ☐ layer ☐ others

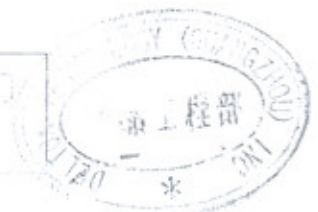
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製程品質監控工程圖

06KT49360B0A COMP



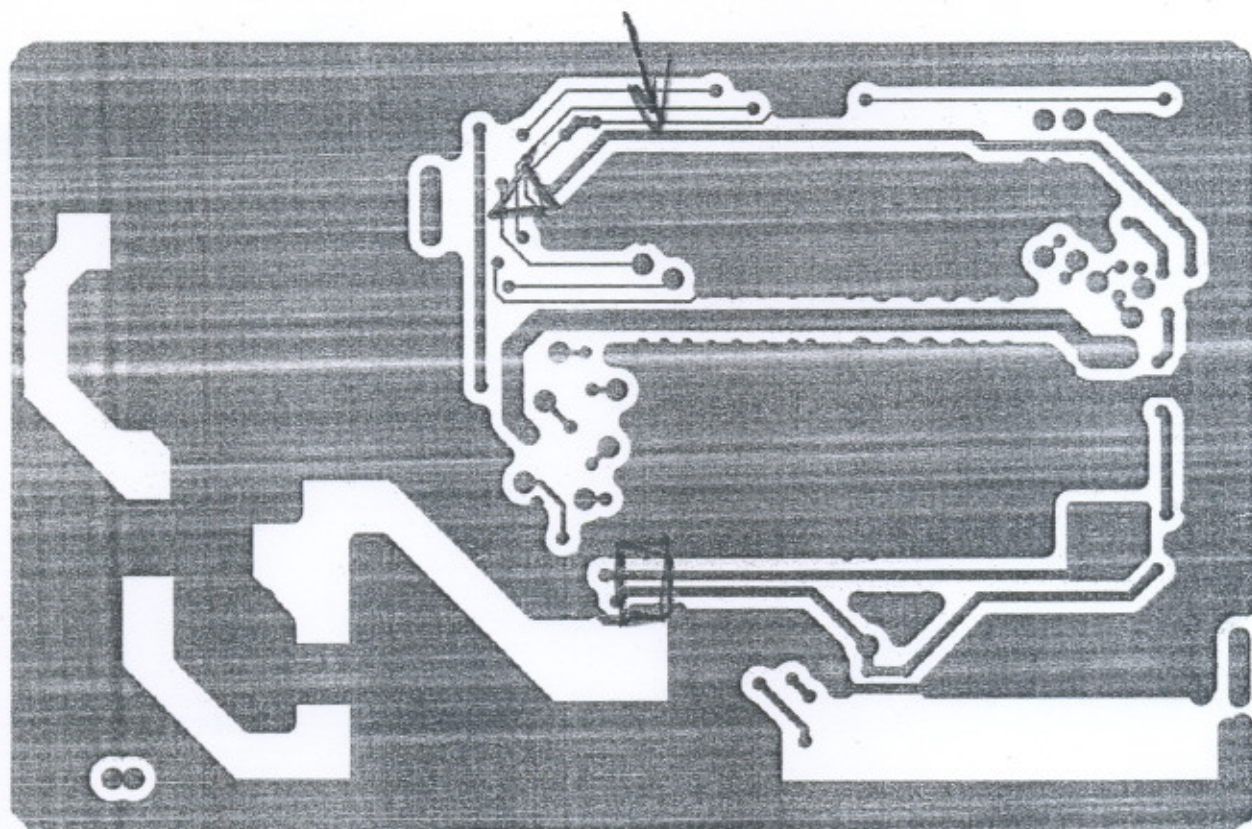
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Pad to Line=> 4 (BGA) Pad Size=> 1496



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製程品質監控工程圖

06KT49360B0A L2



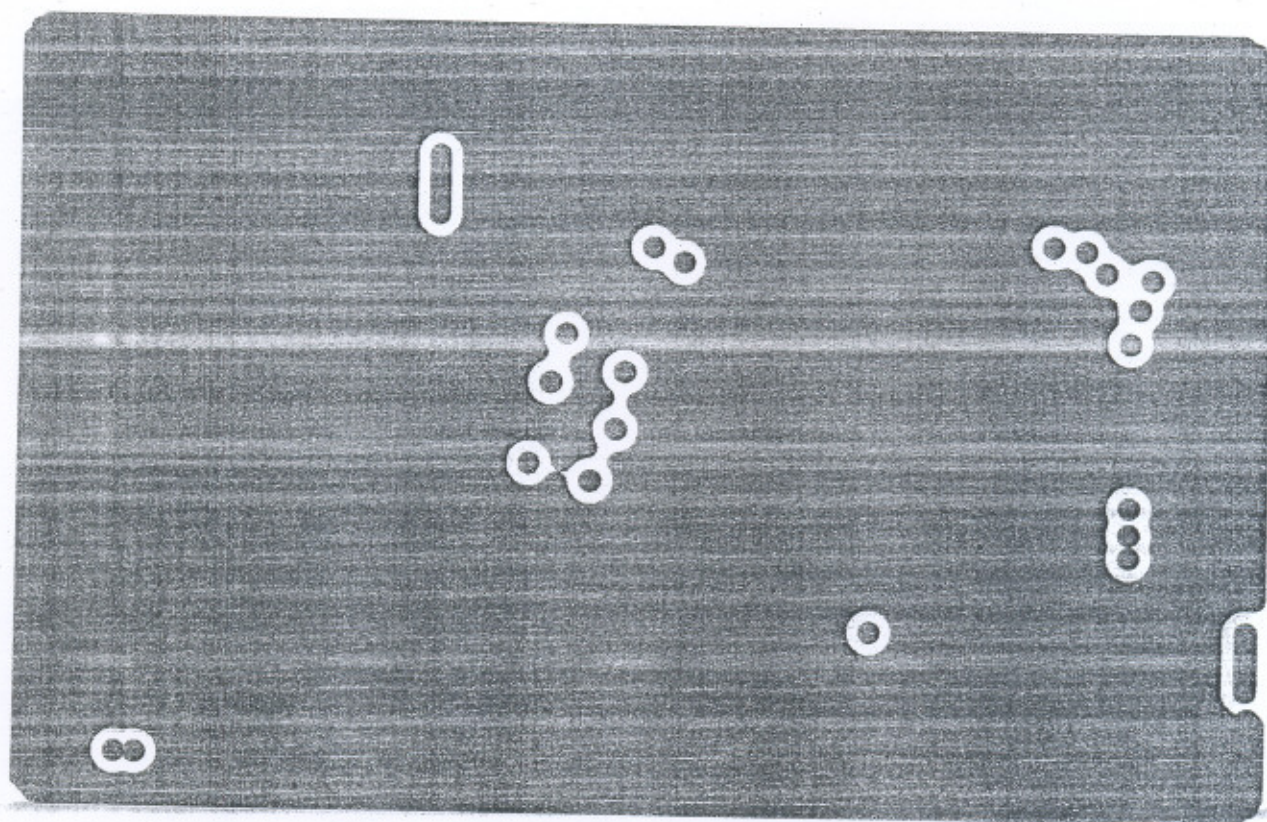
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Pad to Line=> 4 (BGA) Pad Size=> \



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製程品質監控工程圖

06KT49360B0A L3



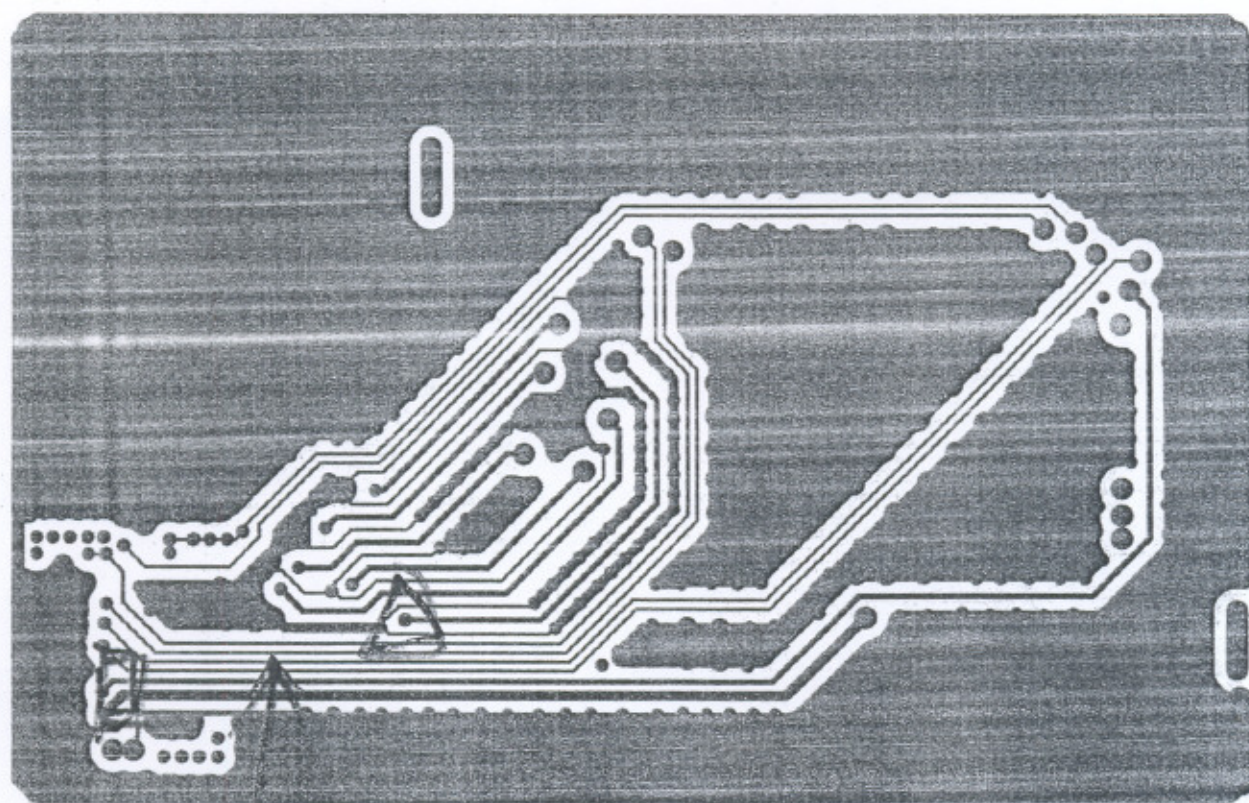
Minimum: Unit: mil Line Width=> _____ Line to Line=> _____
Pad to Line=> _____ (BGA) Pad Size=> _____



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製程品質監控工程圖

06KT49360B0A L5



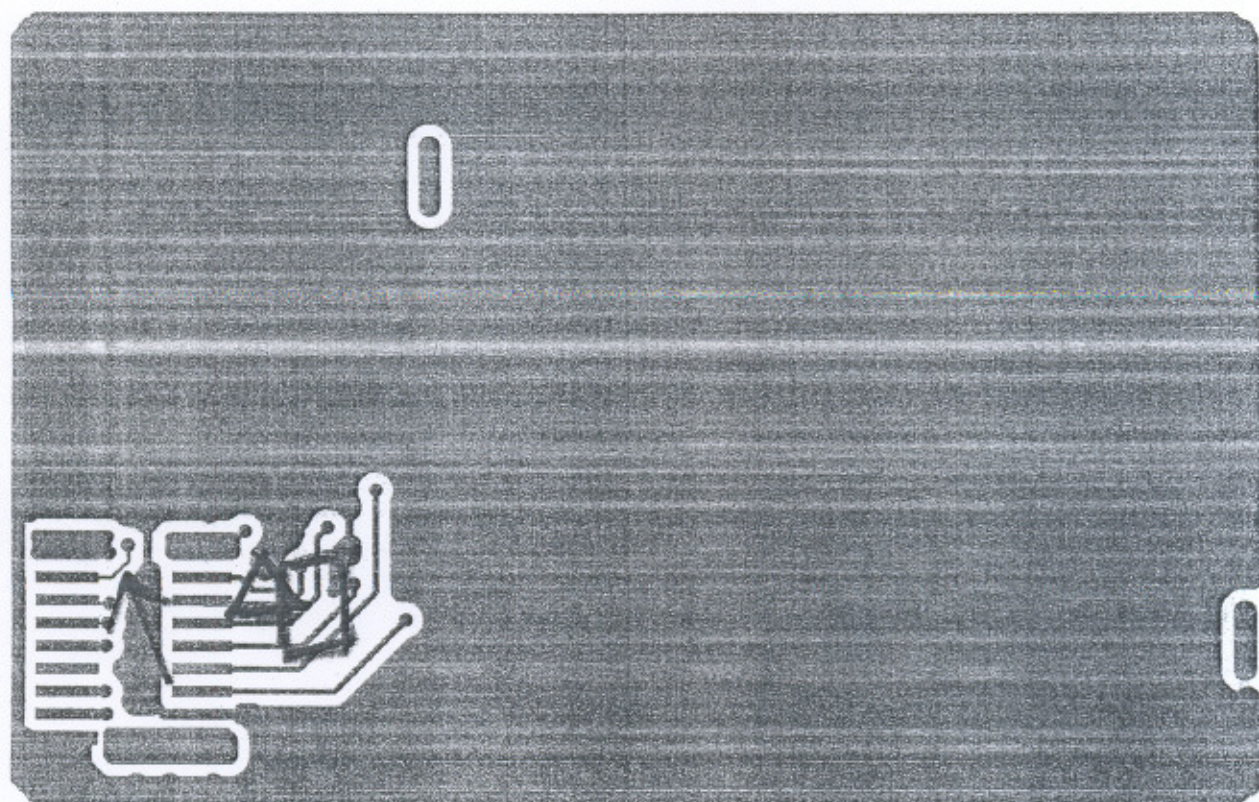
Minimum: Unit:mil Line Width=> 4 Line to Line=> 4
Pad to Line=> 4 (BGA) Pad Size=> \



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製程品質監控工程圖

06KT49360B0A SOLD



Minimum: Unit: mil Line Width=> 4 Line to Line=> 6.002
Pad to Line=> 4 (BGA) Pad Size=> -

